



VMDSEMI

**VUTL008R120NA**

**Datasheet**

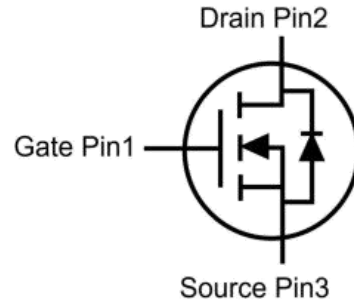


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## General Description

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
80V	12mΩ@10V	68A
	14mΩ@4.5V	

## Symbol



Symbol of VUTL008R120NA

## Features

- Low  $R_{DS(ON)}$
- Enhance Mode
- High conversion efficiency
- Pb-free lead plating; RoHS compliant
- Fast Switching

## Package Type



**TO-252**

Package Type of VUTL008R120NA

## Application

- Motor driver
- High Power inverter system
- Switched mode power supply

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## Ordering Information

Product Name	Package
VUTL008R120NA	TO-252

**Absolute Maximum Ratings** ( $T_A=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	80	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Continuous Drain Current $T_C=25^\circ\text{C}$	$I_D$	68	A
Continuous Drain Current $T_A=70^\circ\text{C}$		44	A
Pulsed Drain Current <sup>Note1</sup> $T_C=25^\circ\text{C}$	$I_{D,pulse}$	260	A
Continuous Diode Forward Current $T_C=25^\circ\text{C}$	$I_S$	68	A
Max Power Dissipation $T_A=25^\circ\text{C}$	$P_D$	83	W
Avalanche Energy, Single Pulse <sup>Not 2</sup>	$E_{AS}$	156	mJ
Operation and storage temperature	$T_J, T_{STG}$	-55 to 175	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	1.8	-	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	-	50	-	

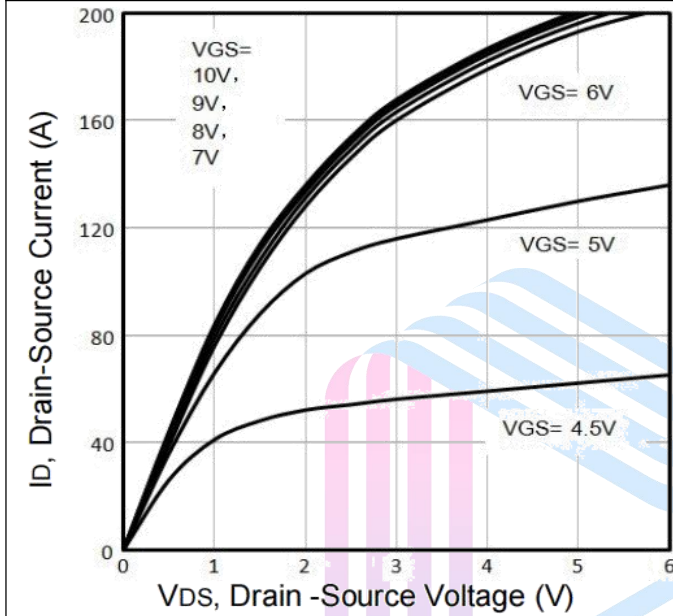
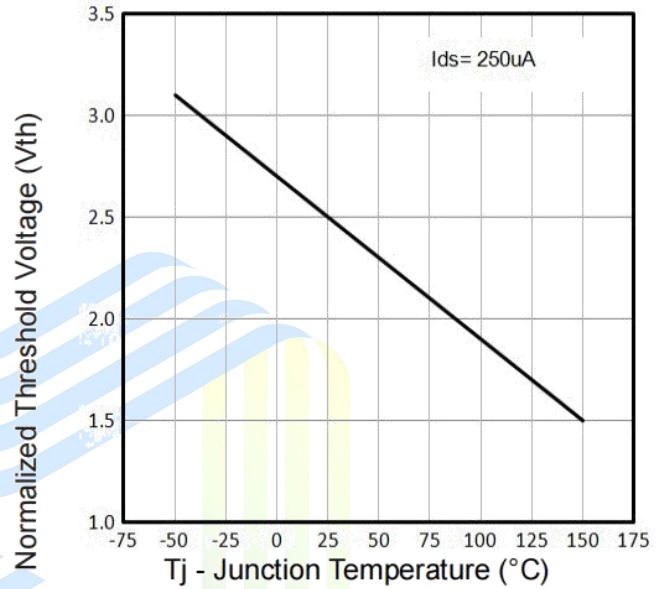
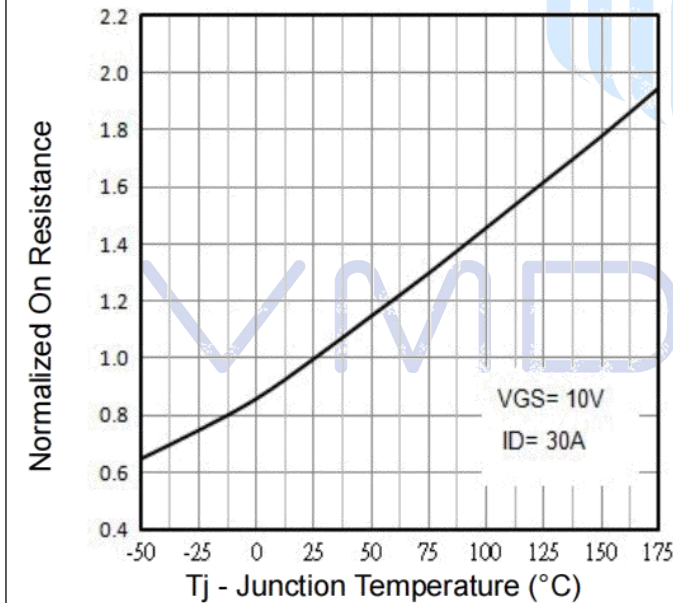
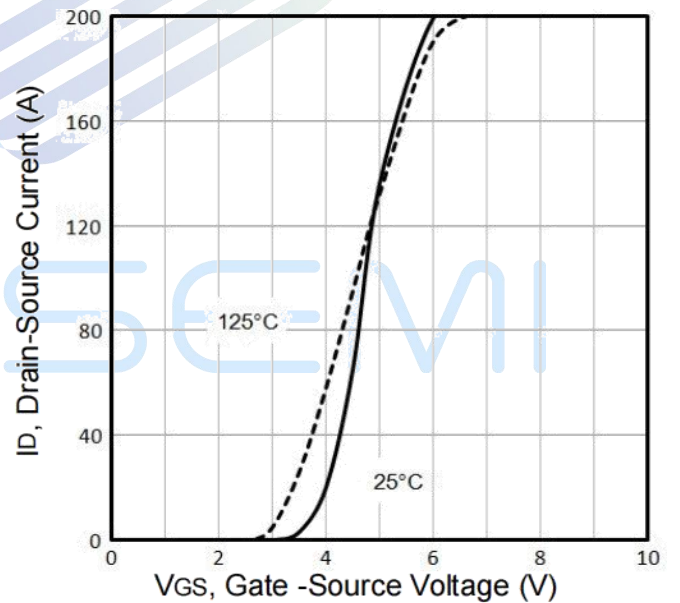
**Electrical Characteristics**( $T_C=25\text{ }^\circ\text{C}$ , unless otherwise specified)

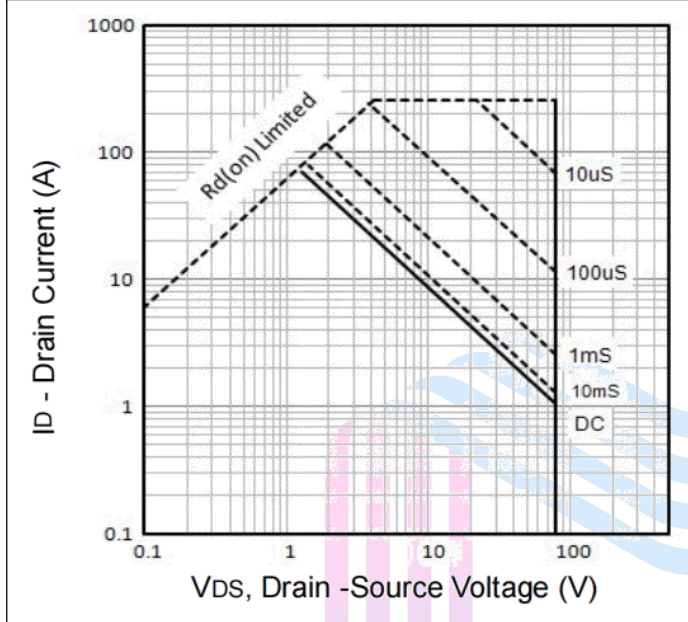
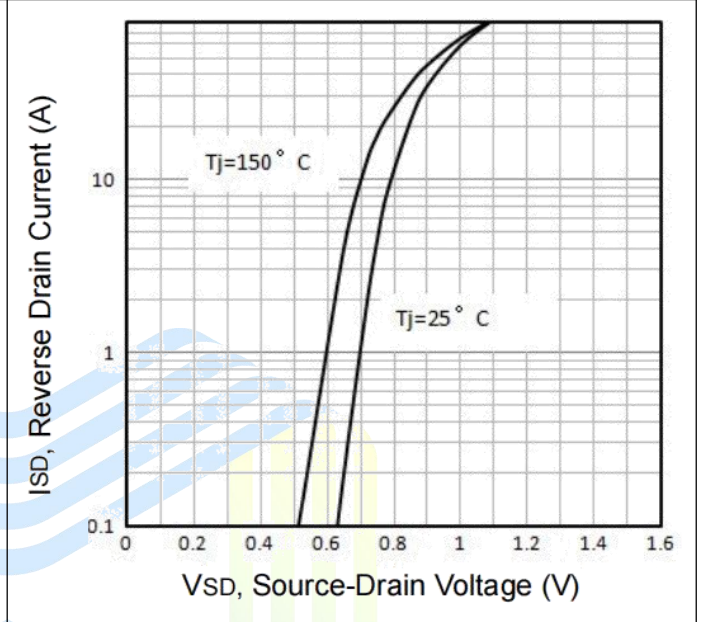
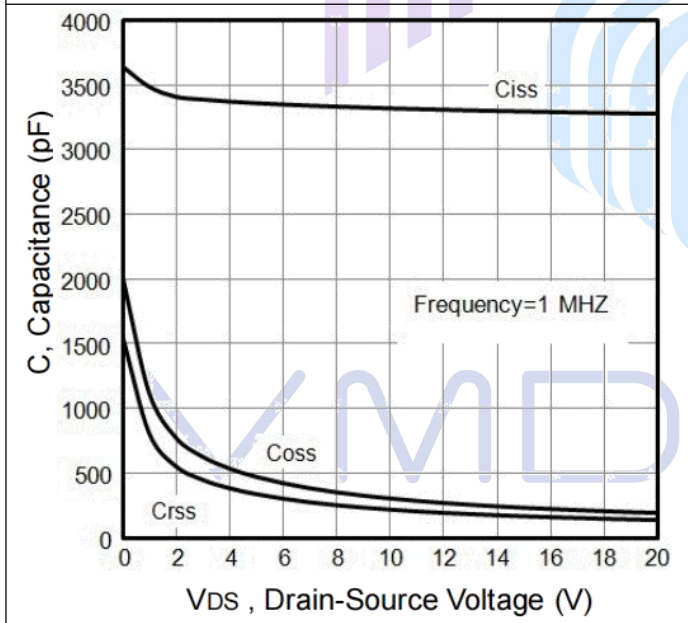
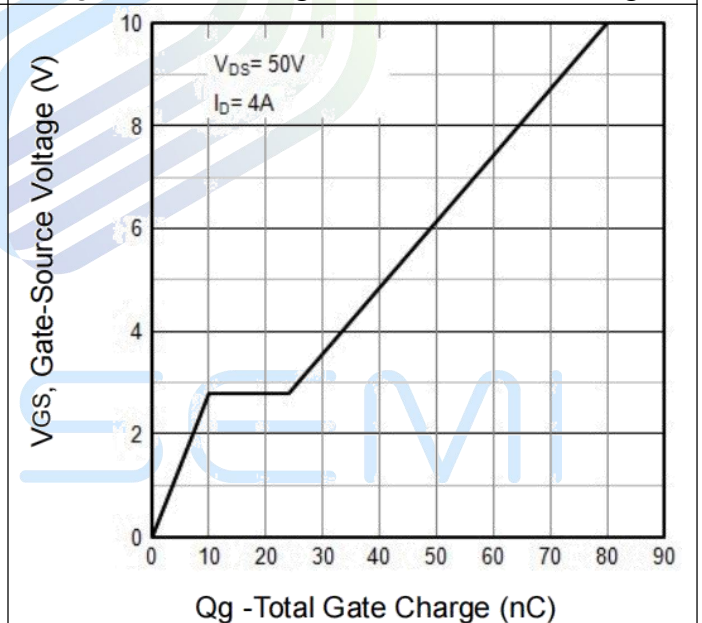
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
Zero Gate Voltage Drain Current $T_J=25\text{ }^\circ\text{C}$	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$	-	-	1	$\mu A$
Zero Gate Voltage Drain Current $T_J=125\text{ }^\circ\text{C}$		$V_{DS}=80V, V_{GS}=0V$	-	-	100	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.3	-	2.5	V
Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=50A$	-	9	12	mΩ
		$V_{GS}=4.5V, I_D=20A$	-	11	14	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{DS}=20V$	-	3280	-	pF
Output Capacitance	$C_{OSS}$	$V_{GS}=0V$	-	195	-	pF
Reverse Transfer Capacitance	$C_{RSS}$	$f=1MHz$	-	130	-	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V$	-	24	-	ns
Rise Time	$t_r$	$I_D=4A$	-	112	-	
Turn-off Delay Time	$t_{d(off)}$	$R_G=6.8\Omega$	-	51	-	
Fall Time	$t_f$	$V_{GS}=10V$	-	105	-	
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	$Q_{gs}$	$V_{GS}=10V$	-	10	-	nC
Gate to Drain Charge	$Q_{gd}$	$V_{DS}=50V$	-	14	-	
Gate Charge Total	$Q_g$	$I_D=4A$	-	80	-	
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_{SD}=40A$	-	0.88	1.2	V
Reverse Recovery Time	$t_{rr}$	$I_{SD}=4A, V_{GS}=0V$	-	33	-	ns
		$T_J=25\text{ }^\circ\text{C}$	-	42	-	nC
Reverse Recovery Charge	$Q_{rr}$	$di/dt=100A/\mu s$	-	42	-	nC

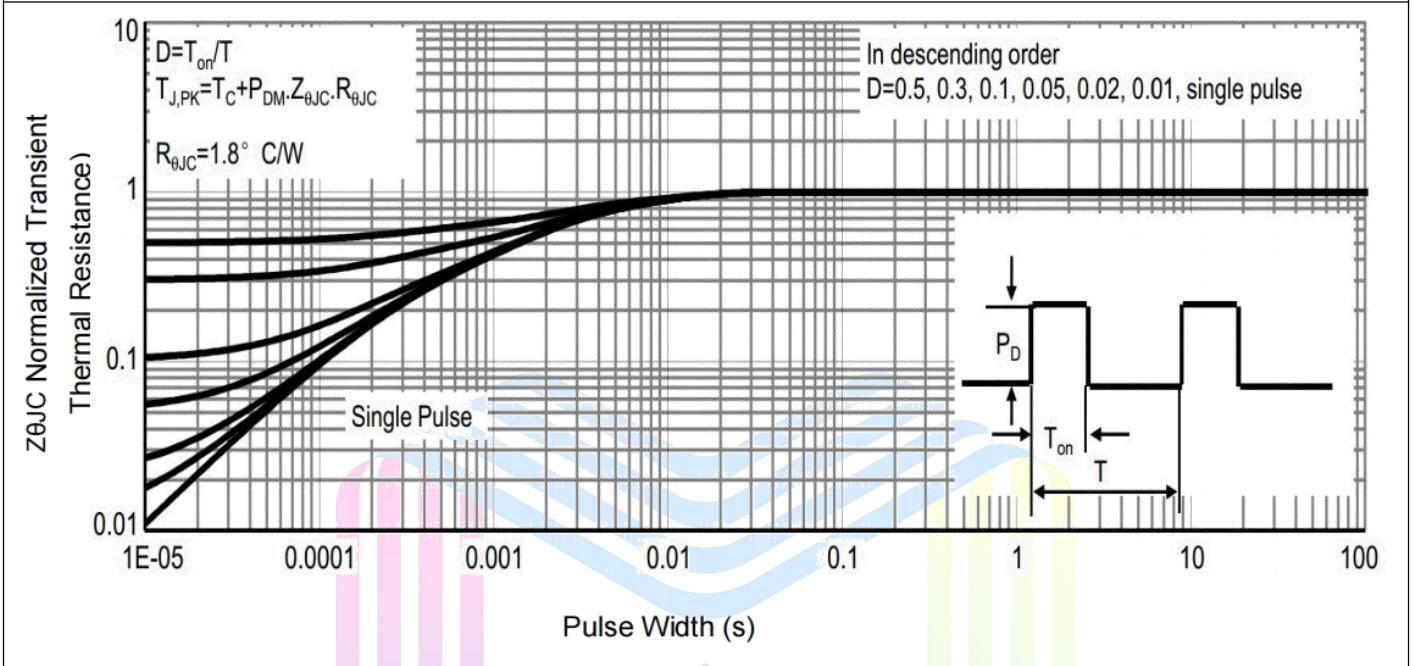
Notes:

1. Repetitive rating; pulse width limited by max. junction temperature.
2. Limited by  $T_{Jmax}$ , starting  $T_J=25\text{ }^\circ\text{C}$ ,  $L=0.5mH$ ,  $R_G=25\Omega$ ,  $I_{AS}=25A$ ,  $V_{GS}=10V$ .
3. Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .

## Typical Performance Characteristics

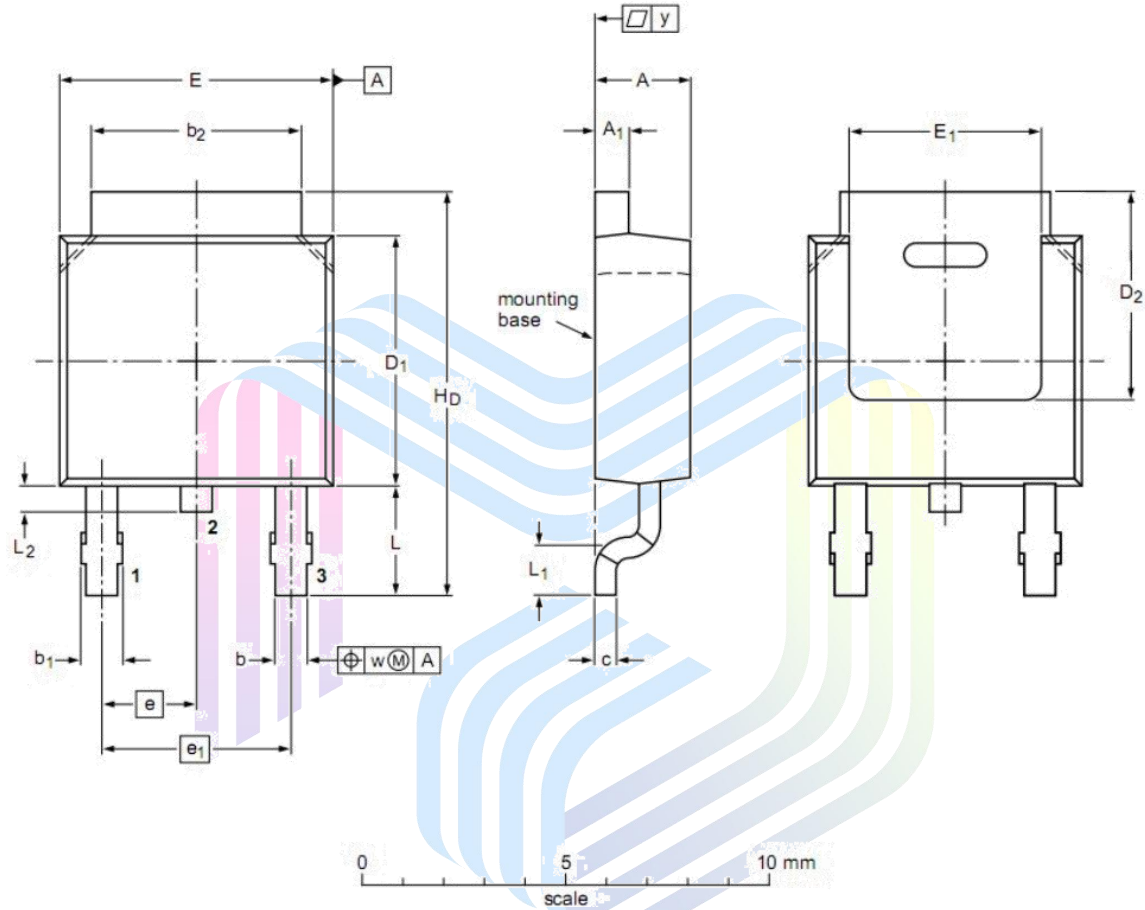
**Figure 1: Typ. Output Characteristics**

**Figure 2: Normalized Threshold Voltage Vs. Temperature**

**Figure 3: Normalized On-State Resistance**

**Figure 4: Typ. Transfer Characteristics**


**Figure 5: Maximum Safe Operating Area**

**Figure 6: Forward Characteristics of Body Diode**

**Figure 7: Capacitance Vs. Drain-Source Voltage**

**Figure 8: Gate Charge Vs. Gate-Source Voltage**


**Figure 9: Normalized Maximum Transient Thermal Impedance**



## Mechanical Dimensions

### Package Information TO-252



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	2.20	2.30	2.38
A <sub>1</sub>	0.46	0.50	0.63
b	0.64	0.76	0.89
b <sub>1</sub>	0.77	0.85	1.14
b <sub>2</sub>	5.00	5.33	5.46
c	0.458	0.508	0.558
D <sub>1</sub>	5.98	6.10	6.223
D <sub>2</sub>	5.21	--	--
E	6.40	6.60	6.731
E <sub>1</sub>	4.40	--	--
e	2.286 BSC		
e <sub>1</sub>	--	4.57	--
H <sub>D</sub>	9.40	10.00	10.40
L	2.743 REF		
L <sub>1</sub>	1.40	1.52	1.77
L <sub>2</sub>	0.50	0.80	1.01
w	--	0.20	--
y	--	--	0.20



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